



INTRODUCTION TO MICROSYSTEM PACKAGING TECHNOLOGY

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Contents

Chapter 1 Introduction	1
1.1 What Are Microsystems?	1
1.2 Related Fundamentals of Microsystems	2
1.2.1 Microelectronics Technology	2
1.2.2 RF and Wireless	2
1.2.3 Optical Electronics	2
1.2.4 Microelectro-mechanical Systems	3
1.3 What Is Microsystems Packaging?	3
1.4 What Is Microelectronics Packaging?	5
1.5 History of Microelectronics Packaging	6
1.6 Status and Function of Microsystems Packaging Technology	7
1.7 Technical Challenges in Microsystems Packaging	8
References	10
Chapter 2 Design Technique for Microsystems Packaging and Integration	11
2.1 Electrical Design	11
2.1.1 Overview of the Electrical Design in Packaging	11
2.1.2 Fundamentals and Flowchart of Electrical Design	11
2.1.3 Analysis of a Package's Electrical Performance	13
2.2 Thermal Management Design	18
2.2.1 Overview of Thermal Management	18
2.2.2 Importance of Thermal Management	18
2.2.3 Basics of Thermal Management	19
2.2.4 Electronic Cooling Methods	22
2.3 Mechanical Design	25
2.3.1 Importance of Mechanical Design	25
2.3.2 Basic Concept in Mechanical Design	26
2.3.3 Mechanical Design Method	26
2.4 Microfluidic Design	29
2.4.1 Introduction to Microfluidic Design	29
2.4.2 Flow in Microchannel	29
2.4.3 Application Example of Microfluidic Package	30
2.5 Multidisciplinary Design	31
2.5.1 Overview	31
2.5.2 Multidisciplinary Designing Methodologies	32
2.5.3 The System-level Simulation by Building Macromodels	33
References	34
Chapter 3 Substrate Technology	37
3.1 Introduction	37
3.2 Organic Substrate	38
3.2.1 Introduction	38
3.2.2 Fabrication Processes of PWB	38
3.2.3 Application of PWB Substrates in MCM	41
3.3 Ceramic Substrates	41
3.3.1 Classification and Fundamental Properties	41

3.3.2	Fabrication of Ceramic Substrates	42
3.4	Introduction of Typical Ceramic Substrates	45
3.4.1	Al ₂ O ₃ Substrate	45
3.4.2	AlN Substrate	46
3.4.3	Mullite Substrate	46
3.4.4	SiC Substrate	47
3.4.5	BeO Substrate	48
3.5	LTCC Substrates	49
3.5.1	Properties of LTCC Substrates	50
3.5.2	Classification and Characteristics of LTCC	50
3.5.3	LTCC Substrate Fabrication Process	51
3.6	Advanced Substrates	55
3.6.1	Substrates with Elements and Channels Embedded	55
3.6.2	High-density Interconnection Substrates	58
3.6.3	Flexible Substrate	59
	References	61
Chapter 4	Interconnection Technology	65
4.1	Introduction	65
4.2	Braze-welding Technology	65
4.3	Wire-bonding Technology	67
4.3.1	Basic Concept	67
4.3.2	Types of Wire Bonding	67
4.3.3	Materials Used in Wire Bonding	68
4.3.4	Key Process Parameters of Wire Bonding	69
4.3.5	Technical Limitations	71
4.4	Tape Automated Bonding Technology	71
4.4.1	Basic Concept	71
4.4.2	Essential Techniques	71
4.4.3	Technical Features	73
4.5	Flip-chip Bonding Technology	73
4.5.1	Basic Concept	73
4.5.2	Bonding Process	74
4.5.3	Main Materials of Flip-chip Bonding	75
4.5.4	Reliability of Flip-chip Bonding	76
4.6	Chip Interconnection in System-level Packaging	78
4.6.1	Chip Interconnection in MCM	78
4.6.2	Interconnection in SIP	79
4.7	Advanced Interconnection	79
4.7.1	Nano interconnection	79
4.7.2	3D Interconnection	81
	References	83
Chapter 5	Device-level Packaging	87
5.1	Introduction	87
5.1.1	Basic Concepts	87
5.1.2	Status and Role	87
5.1.3	History	88
5.2	Metal Packaging	89
5.2.1	Concept of Metal Packaging	89
5.2.2	Advantages of Metal Packaging	90
5.2.3	Process of Metal Packaging	90

5.2.4	Traditional Metal Packaging Materials	91
5.2.5	Novel Metal Packaging Materials	92
5.2.6	A Case Study of Metal Packaging	92
5.3	Plastic Packaging	93
5.3.1	Concepts and Features of Plastic Packaging	93
5.3.2	Working Process and Procedures of Plastic Packaging	93
5.3.3	Types of Plastic Packaging	94
5.4	Ceramic Packaging	95
5.4.1	Profile of Ceramic Packaging	95
5.4.2	Process of Ceramic Packaging	95
5.4.3	Types of Ceramic Packaging	96
5.4.4	An Example of Ceramic Packaging Application—High Brightness LED Package	96
5.5	Typical Examples of Device-level Packaging	96
5.5.1	DIP	96
5.5.2	BGA Packaging	97
5.5.3	CSP	100
5.6	Development Prospects	105
	References	105
Chapter 6	MEMS Packaging	107
6.1	Introduction	107
6.2	Function of MEMS Packaging	108
6.2.1	Mechanical Support	108
6.2.2	Device Protection	109
6.2.3	Electrical Interconnections	110
6.3	Device-level Package for MEMS	110
6.3.1	Metal Packages	110
6.3.2	Ceramic Packaging	111
6.3.3	Plastic Packaging	112
6.4	Wafer-level Package for MEMS	112
6.5	Sealing Techniques	113
6.5.1	Introduction	113
6.5.2	Eutectic Bonding and Solder Bonding	113
6.5.3	Adhesive Bonding	114
6.5.4	Glass Frit Bonding	115
6.5.5	Anodic Bonding	115
6.5.6	Fusion Bonding	115
6.6	Thin-film Encapsulation	116
6.7	Vacuum Packaging for MEMS	117
6.7.1	Vacuum Maintenance for MEMS Packaging	117
6.7.2	Leakage Detection	119
6.8	Case Study: A 3D Wafer-level Hermetic Packaging for MEMS	119
6.8.1	Design and Fabrication Process	119
6.8.2	Experiments and Results	120
	References	122
Chapter 7	Module Assembly and Optoelectronic Packaging	125
7.1	Introduction	125
7.2	Surface Mount Technology	125
7.2.1	Features	126
7.2.2	Basic Assembly Processes and Work Flow	127
7.2.3	Material and Cleaning Processes	128

7.2.4	Surface Mount Components	128
7.2.5	SMT Design	129
7.2.6	SMT Testing	130
7.3	Packaging of Flat Panel Display Modules	132
7.3.1	Introduction of Liquid Crystal Display	132
7.3.2	Packaging of Display Modules	132
7.3.3	Chip-on-glass (COG) Packaging	134
7.3.4	Chip-on-foil (COF) Packaging	137
7.3.5	Foil-on-glass Thermal Compression Bonding	138
7.4	Optoelectronic Packaging	139
7.4.1	Laser Diode Packaging	139
7.4.2	LED Packaging Technology	140
7.4.3	Optoelectronic Coupling and Fixation	142
	References	145
Chapter 8	System-level Packaging Technology	147
8.1	Overview	147
8.2	System on Chip Technology	147
8.2.1	Overview	147
8.2.2	SOC Samples	148
8.2.3	Problems, Challenges, and Solutions	150
8.3	System in Package Technology	152
8.3.1	Overview	152
8.3.2	SIP Technology	153
8.3.3	Comparison between System-on-chip and System-in-package	156
8.4	RF System Package Technology	157
8.4.1	Overview	157
8.4.2	The Features and Roles of RF MEMS Package	160
8.4.3	Categorization of RF MEMS Package	162
8.4.4	Materials for RF MEMS Packaging	164
8.4.5	Chip-to-package and On-chip Interconnection	165
8.4.6	Hot Topics in RF Microsystems Packaging	167
	References	168
Chapter 9	Reliability	173
9.1	Introduction	173
9.2	Fundamentals of Reliability Methodology	174
9.2.1	Basic Reliability Theory	175
9.2.2	Distribution Used in Reliability Analysis	176
9.3	Wafer and Packaging-related Failure Mode and Mechanisms	179
9.3.1	Wafer-related Failures and Mechanisms	180
9.3.2	Packaging-related Failures and Mechanisms	182
9.3.3	MEMS-related Failures and Mechanisms	183
9.4	Reliability Qualification and Analysis	184
9.4.1	Accelerating Test	184
9.4.2	Failure Mechanism Models	185
9.4.3	Reliability-related Standards	187
9.4.4	Reliability Test Methods	188
9.4.5	Case Study I: Solder Joint Design Methodology	192
9.4.6	Case Study II	196
9.5	Summary	199
	References	199

Chapter 10	Prospects for Microsystems Packaging Technology	203
10.1	Evolution of Packaging Materials	203
10.2	Evolution and Application of Packaging Technologies	204
10.2.1	Ball-grid Array (BGA) Package and Chip-scale Package	204
10.2.2	Flip-chip Technology	205
10.2.3	3D Packaging	205
10.2.4	Multichip Module	206
10.2.5	System in Package	207
10.2.6	New Areas for Packaging Technology Development	208
10.3	Evolution of Packaging Technologies and Environmental Protection	210
10.3.1	Electronic Waste Pollution	210
10.3.2	Control at Workshops	211
10.3.3	Electronic Waste Treatment	212
10.4	Concluding Remarks	213
	References	214
Index		215